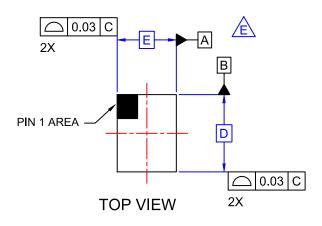
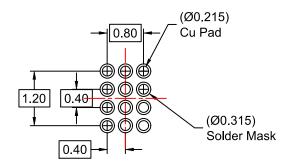


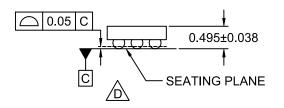
WLCSP12 1.3x1.8x0.495 CASE 567RA ISSUE O

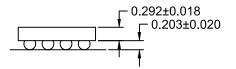
DATE 31 OCT 2016



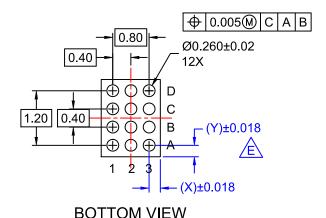


RECOMMENDED LAND PATTERN (NSMD PAD TYPE)





SIDE VIEWS



NOTES:

- A. NO JEDEC REGISTRATION APPLIES.
- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 2009.
- D.DATUM C IS DEFINED BY THE SPHERICAL CROWNS OF THE BALLS.
- FOR DIMENSIONS D, E, X, AND Y SEE PRODUCT DATASHEET.

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DESCRIPTION:	WLCSP12 1.3x1.8x0.495		PAGE 1 OF 1

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